1214GN-700V

**Datasheet** 

**Class-AB GaN-on-SiC HEMT Transistor** 







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# **Revision History**

The revision history describes the changes that were implemented in the document. The changes are listed by revision, starting with the most current publication.

## **1.1** Revision **1.0**

Revision 1.0 was published in March 2017. It was the first publication of this document.



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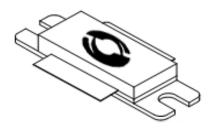


### 2 Product Overview

The 1214GN-700V is an internally matched, common-source, class-AB GaN-on-SiC HEMT transistor capable of providing over 18 dB gain, 700 W of pulsed RF output power at 300  $\mu$ s pulse width, and 10% duty factor across the 960 MHz to 1215 MHz band. The transistor has internal pre-match for optimal performance. This hermetically sealed transistor is designed for the output stage of L-Band pulsed primary radar systems. It utilizes gold metallization and eutectic die attach to provide the highest reliability and superior ruggedness.

The export classification is EAR-99.

Figure 1 1214GN-700V Case Outline





## **3** Electrical Specifications

This section details the electrical specifications of the of the 1214GN-700V device.

### 3.1 Absolute Maximum Ratings

The following table shows the absolute maximum ratings of the 1214GN-700V device.

**Table 1 Absolute Maximum Ratings** 

Rating	Parameter	Value	Units
Maximum power dissipation	Device dissipation at 25 °C		W
Maximum voltage and current	Drain-source voltage (V <sub>DSS</sub> )	150	٧
	Gate-source voltage (V <sub>GS</sub> )	-8 to 0	٧
Maximum temperatures	Storage temperature (T <sub>STG</sub> )	–55 to 125	°C
	Operating junction temperature	200	°C

#### 3.2 Electrical Characteristics

The following table shows the typical electrical characteristics of the 1214GN-700V device at 25 °C.

**Table 2 Electrical Characteristics** 

Symbol	Characteristics	Test Conditions	Min	Тур	Max	Units
P <sub>OUT</sub>	Output power	Freq = 960 MHz, 1090 MHz, 1215 MHz	700	750		W
G <sub>P</sub>	Power gain	P <sub>IN</sub> = 12 W, Freq = 960 MHz, 1090 MHz, 1215 MHz	16	16.5		dB
η <sub>D</sub>	Drain efficiency	P <sub>IN</sub> = 12 W, Freq = 960 MHz, 1090 MHz, 1215 MHz	60	63		%
Dr	Droop	P <sub>IN</sub> = 12 W, Freq = 960 MHz, 1090 MHz, 1215 MHz		0.5		dB
VSWR-T	Load mismatch tolerance	P <sub>IN</sub> = 12 W, Freq = 1215 MHz			3:1	
θ <sub>JC</sub>	Thermal resistance	Pulse width = 300 μs; Duty = 10%			0.22	°C/W

Bias Condition:  $V_{DD} = 50 \text{ V}$ ,  $I_{DQ} = 100 \text{ mA}$  constant current ( $V_{GS} = -2.0 \text{ V}$  to -4.5 V) with constant gate bias

#### 3.3 Functional Characteristics

The following table shows the typical functional characteristics of the 1214GN-700V device at 25 °C.

**Table 3 Functional Characteristics** 

Symbol	Characteristics	Test Conditions	Min	Тур	Max	Units
I <sub>D(Off)</sub>	Drain leakage current	$V_{GS} = -8 \text{ V}, V_D = 150 \text{ V}$			64	mA
I <sub>G(Off)</sub>	Gate leakage current	$V_{GS} = -8 \text{ V}, V_D = 0 \text{ V}$			22	mA



### 3.4 Typical Broadband Performance Data

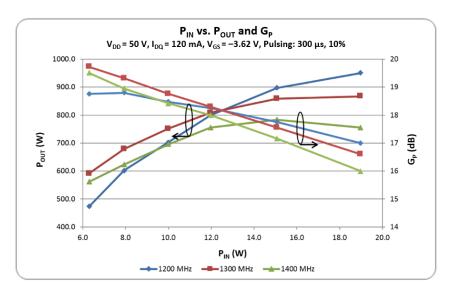
The following table shows the typical broadband performance data of the 1214GN-700V device, where the pulse width is 300  $\mu$ s and the duty factor is 10%. In the following table,  $V_{DD}$  = 50 V,  $V_{GS}$  = 3.62 V, and  $I_{DQ}$  = 120 mA.

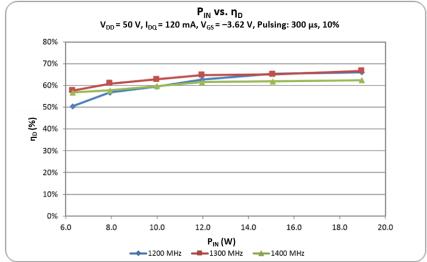
**Table 4 Typical Broadband Performance Data** 

Freq (GHz)	P <sub>IN</sub> (W)	P <sub>OUT</sub> (W)	G <sub>P</sub> (dB)	I <sub>D</sub> (mA)	Droop (dB)	η <sub>D</sub> (%)
1.2	12.0	799.8	18.25	2.67	0.5	71
1.3	12.0	809.1	18.30	2.62	0.45	63
1.4	12.0	755.1	18	2.57	0.4	62

The following graphs show the typical broadband performance of the 1214GN-700V device.

Figure 2 Typical Broadband Performance Data Graphs







# 4 Package Information

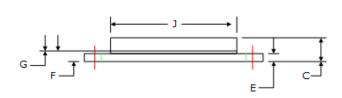
This section details the package information of the 1214GN-700V device.

## 4.1 55-Q03 Package

The following illustration shows the 55-Q03 package outline of the 1214GN-700V device. PIN 1 is the drain, PIN 2 is the source, and PIN 3 is the gate.

K A M

Figure 3 55-Q03 Package Outline



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The following table shows the 55-Q03 dimensions of the 1214GN-700V device.

Table 5 55-Q03 Package Dimensions

Dimension	Millimeters	Tol (mm)	Inches	Tol (in.)
Α	34.03	0.25	1.340	0.010
В	9.78	0.25	0.385	0.010
С	3.55	0.19	0.140	0.007
D	12.70	0.13	0.500	0.005
E	1.02	0.13	0.040	0.005
F	1.65	0.13	0.065	0.005
G	0.13	0.03	0.005	0.001
Н	19.43	0.76	0.765	0.030
I	45°	5°	45°	5°



Dimension	Millimeters	Tol (mm)	Inches	Tol (in.)
J	19.81	0.25	0.780	0.030
K	3.30 DIA	0.13	0.130 DIA	0.005
L	9.40	0.13	0.370	0.005
М	27.94	MAX	1.100	MAX